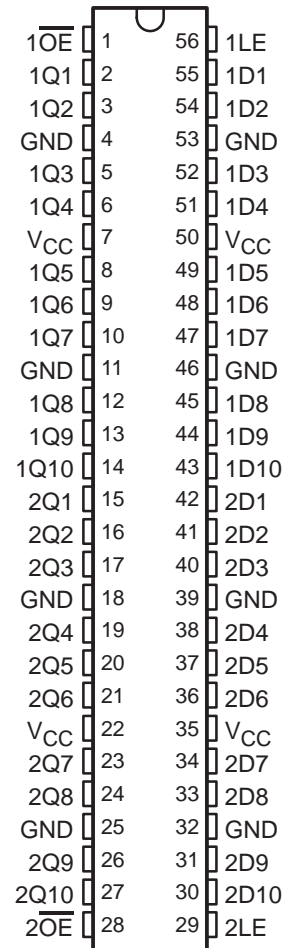


SN54ABT162841, SN74ABT162841 20-BIT BUS-INTERFACE D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS665C – JUNE 1996 – REVISED JUNE 2004

- Members of the Texas Instruments Widebus™ Family
- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- I_{off} and Power-Up 3-State Support Hot Insertion
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17

SN54ABT162841 . . . WD PACKAGE
SN74ABT162841 . . . DGG OR DL PACKAGE
(TOP VIEW)



description/ordering information

These 20-bit transparent D-type latches feature noninverting 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The 'ABT162841 devices can be used as two 10-bit latches or one 20-bit latch. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74ABT162841DL	ABT162841
		Tape and reel	SN74ABT162841DLR	
	TSSOP – DGG	Tape and reel	SN74ABT162841DGGR	ABT162841
-55°C to 125°C	CFP – WD	Tube	SNJ54ABT162841WD	SNJ54ABT162841WD

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN54ABT162841, SN74ABT162841 20-BIT BUS-INTERFACE D-TYPE LATCHES WITH 3-STATE OUTPUTS

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description/ordering information (continued)

A buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

The outputs, which are designed to sink up to 12 mA, include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

To ensure the high-impedance state during power up or power down, \overline{OE} shall be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

\overline{OE} does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

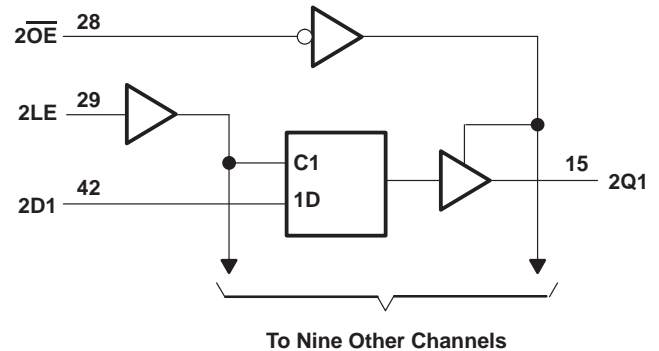
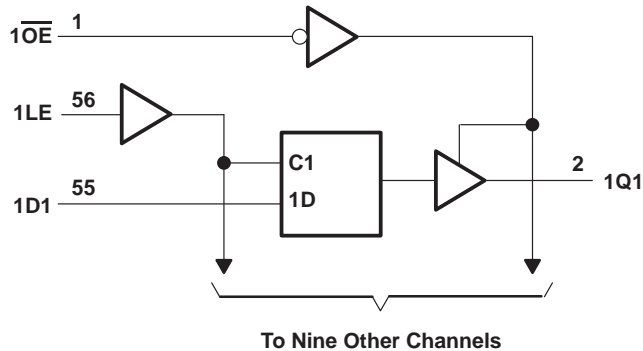
FUNCTION TABLE
(each 10-bit latch)

INPUTS			OUTPUT
\overline{OE}	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

SN54ABT162841, SN74ABT162841 20-BIT BUS-INTERFACE D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS665C – JUNE 1996 – REVISED JUNE 2004

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	64°C/W
DL package	56°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54ABT162841		SN74ABT162841		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–3		–12	mA
I_{OL}	Low-level output current		8		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μ s/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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SN54ABT162841, SN74ABT162841

20-BIT BUS-INTERFACE D-TYPE LATCHES

WITH 3-STATE OUTPUTS

SCBS665C – JUNE 1996 – REVISED JUNE 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T _A = 25°C			SN54ABT162841		SN74ABT162841		UNIT	
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.2		-1.2		-1.2	V	
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -1 mA			2.5		2.5		2.5	V	
	V _{CC} = 5 V, I _{OH} = -1 mA			3		3		3		
	V _{CC} = 4.5 V	I _{OH} = -3 mA			2.4		2.4			2.4
I _{OH} = -12 mA				2*				2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 8 mA			0.4		0.8	0.65	V	
		I _{OL} = 12 mA			0.8*			0.8		
V _{hys}				100					mV	
I _I	V _{CC} = 0 to 5.5 V, V _I = V _{CC} or GND			±1		±1		±1	µA	
I _{OZPU}	V _{CC} = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$			±50		±50		±50	µA	
I _{OZPD}	V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$			±50		±50		±50	µA	
I _{OZH}	V _{CC} = 2.1 V to 5.5 V, V _O = 2.7 V, $\overline{OE} \geq 2$ V			10		10		10	µA	
I _{OZL}	V _{CC} = 2.1 V to 5.5 V, V _O = 0.5 V, $\overline{OE} \geq 2$ V			-10		-10		-10	µA	
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V			±100				±100	µA	
I _{CEX}	Outputs high	V _{CC} = 5.5 V, V _O = 5.5 V			50		50	50	µA	
I _{O‡}		V _{CC} = 5.5 V, V _O = 2.5 V	-25	-75	-100	-25	-100	-25	-100	mA
I _{CC}	Outputs high	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			0.5		0.5	0.5	mA	
	Outputs low				89		89	89		
	Outputs disabled				0.5		0.5	0.5		
ΔI _{CC} §		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			1.5		1.5	1.5	mA	
C _i		V _I = 2.5 V or 0.5 V			3.5				pF	
C _o		V _O = 2.5 V or 0.5 V			9				pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} = 5 V, T _A = 25°C		SN54ABT162841		SN74ABT162841		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high or low	4		4		4		ns
t _{su}	Setup time, data before LE↓	0.8		0.8		0.8		ns
t _h	Hold time, data after LE↓	1.8		1.8		1.8		ns

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SN54ABT162841, SN74ABT162841
20-BIT BUS-INTERFACE D-TYPE LATCHES
WITH 3-STATE OUTPUTS

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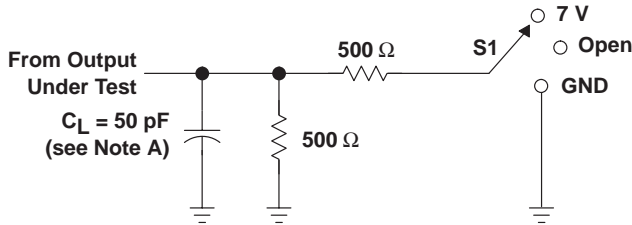
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ$ C			SN54ABT162841		SN74ABT162841		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.1	3.5	4.5	2.1	5.7	2.1	5.2	ns
t_{PHL}			3	4.3	5.3	3	6.2	3	6	
t_{PLH}	LE	Q	2.1	3.5	4.5	2.1	5.6	2.1	5.4	ns
t_{PHL}			2.8	4.1	5.1	2.8	6.1	2.8	5.8	
t_{PZH}	\overline{OE}	Q	2	3.6	4.7	2	5.8	2	5.7	ns
t_{PZL}			3	4.6	5.7	3	6.7	3	6.5	
t_{PHZ}	\overline{OE}	Q	2.6	4.3	5.7	2.6	6.6	2.6	6.5	ns
t_{PLZ}			2.2	3.6	5.8	2.2	8.4	2.2	7.1	

SN54ABT162841, SN74ABT162841
20-BIT BUS-INTERFACE D-TYPE LATCHES
WITH 3-STATE OUTPUTS

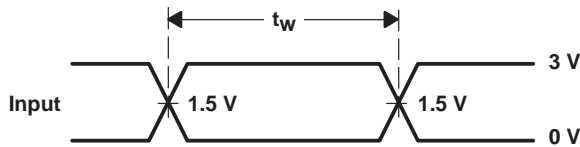
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PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

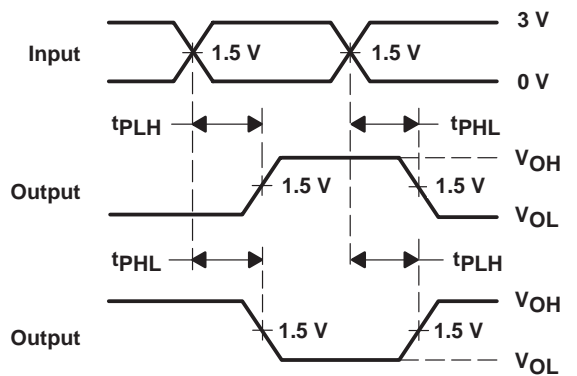
LOAD CIRCUIT



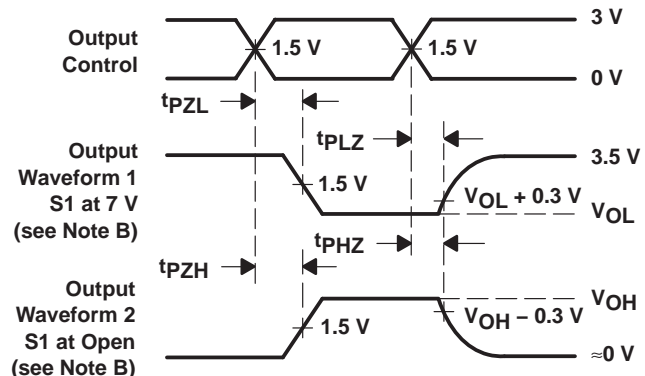
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ABT162841DGGR	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162841
SN74ABT162841DGGR.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162841
SN74ABT162841DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162841
SN74ABT162841DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162841
SN74ABT162841DLR	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162841
SN74ABT162841DLR.B	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162841

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT162841DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1
SN74ABT162841DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT162841DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0
SN74ABT162841DLR	SSOP	DL	56	1000	356.0	356.0	53.0

TUBE

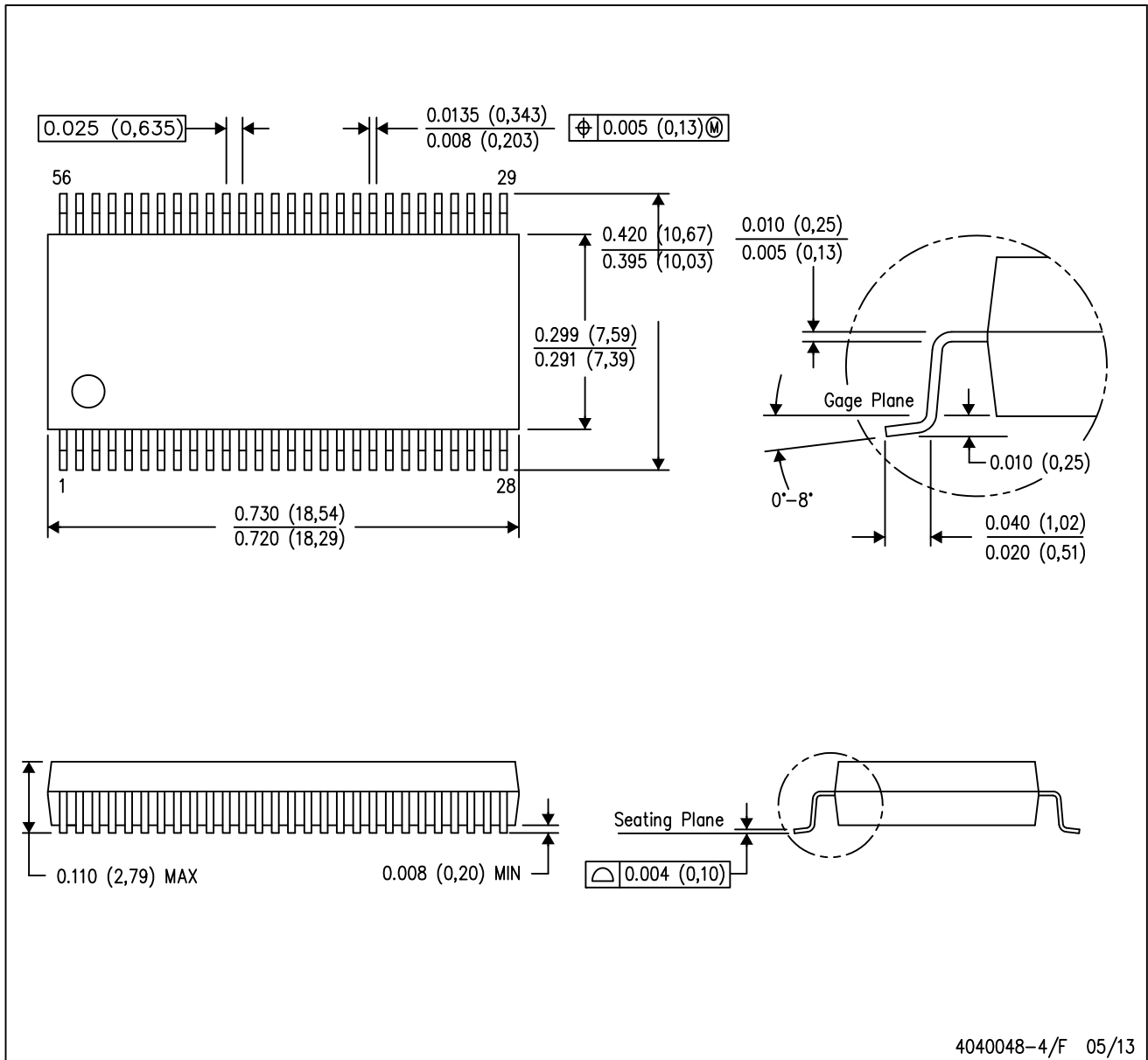

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABT162841DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ABT162841DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

MECHANICAL DATA

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118

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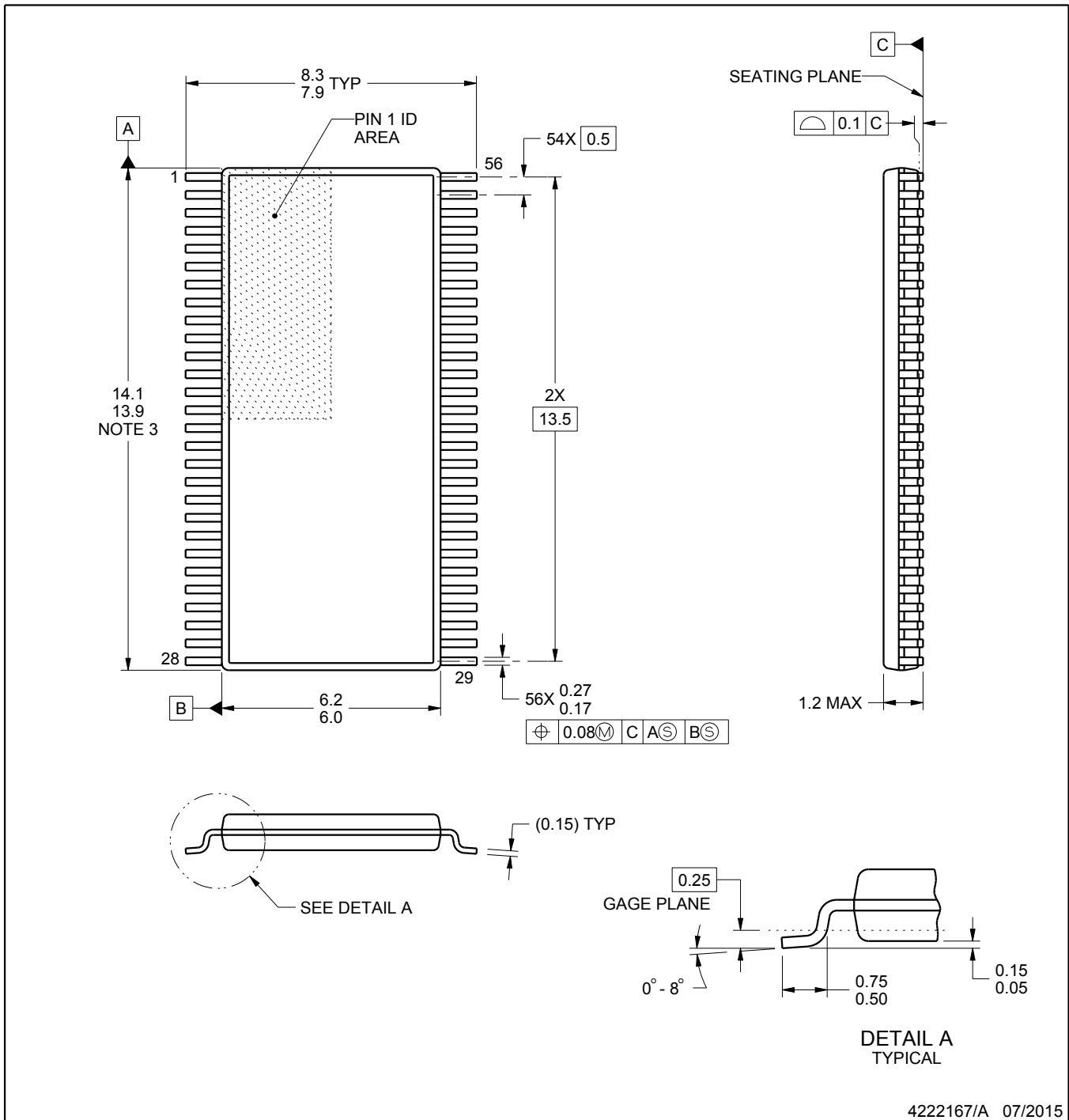
DGG0056A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4222167/A 07/2015

NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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